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With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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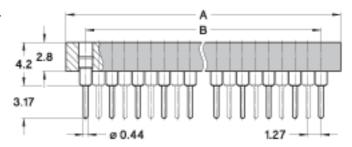
# PGA / BGA / PLCC SOCKETS

SERIES 517 517-PP-NNN-XX-XXX111

**PGA** 

Interstitial socket, Solder tail

Pin grid array sockets with interstitial contact rows, solder tails.



## **TECHNICAL SPECS.:**

Insulator Black glass filled polyester PCT-GF30-FR

Flammability UL 94V-O

Sleeve Brass CuZn36Pb3 (C36000)

Contact Beryllium copper (C17200)

Accepted pin Ø 0.40 to 0.56 mm

**Insertion force** 0.4 N typ.

Withdrawal force 0.2 N typ. (polished steel gauge Ø 0.46 mm)

Mechanical life Min. 100 cycles

Rated current 1 A

Contact resistance Max. 10 m

Dielectric strength Min. 700 V RMS

#### **ORDERING INFORMATION:**

PP Plating code Sleeve Clip
87 Tin Gold flash
83 Tin Gold 0.75 μm

Replace NNN with the number of poles and XX-XXX with body size and layout numbers as indicated here. For example a 19x19 pin configuration with window and 296 contacts as shown here becomes 517-83-296-19-131111. Options: please consult for availability.- PGA sockets with optional standoffs.

### TECHNICAL ASSISTANCE

#### **GENERAL SPECIFICATIONS:**

The values listed below are general specs applying for PRECI-DIP PGA, BGA and PLCC sockets. Please see individual catalog page for additional and product specific technical data.

Operating temperature range -55 ... +125 °C

Climatic category (IEC) 55/125/21

Operating humidity range annual mean 75 %

Max working voltage 100 VRMS/150 VDC (2.54 mm grid)

PRECI-DIP sockets are recognized by Underwriters Laboratories Inc. and listed under "Connectors for Use in Data, Signal, Control and Power Applications", File Nr. E174442

#### MECHANICAL CHARACTERISTICS:

Clip retention Min. 40 N (no displacement under axial force applied)

Contact (sleeve / clip) retention Min. 3.3 N acc. to MIL-DTL-83734, pt 4.6.4.2

#### **ELECTRICAL CHARACTERISTICS:**

Insulation resistance between any two adjacent contacts

Min. 10'000 M at 500 V AC

Capacitance between any two adjacent contacts

Max. 1 pF (PLCC max. 2 pF)

Self inductance per contact Max. 2 nH

#### **ENVIRONMENTAL CHARACTERISTICS:**

The sockets withstand the following environmental tests without mechanical and electrical defects:

- Dry heat steady state IEC 60512-11-9.11i / 60068-2-2.Bb: 125 °C, 16h
- Damp heat cyclic IEC 60512-11-12.11m / 60068-2-30.Db: 25/55 °C, 90 100 %rH, 1 cycle of 24 h
- Cold steady state IEC 60512-11-10.11j / 60068-2-1.A: -55 °C, 2 h
- Thermal shock IEC 60512-11-4.11d / 60068-2-14.Na: -55/125 °C, 5 cycles 30 min
- Sinusoidal vibrations IEC 60512-6-4.6d / 60068-2-6.Fc: 10 to 500 Hz, 10 g, 1 octave/min, 10 cycles for each axis
- Shock IEC 60512-6-3.6c / 60068-2-27.Ea: 50 g, 11 ms, 3 shocks in three axis

During the above two tests no contact interruption >50 ns does appear.

- Solderability J-STD-002A, Test A, 245°C, 5 s solder alloy SnAg3.8Cu0.7
- Resistance to soldering heat J-STD-0020C, 260°C, 20 s
- Moisture sensitivity J-STD-020C level 1
- Resistance to corrosion :
- 1) Salt spray test IEC 60068-2-11.Ka: 48 h
- 2) Sulfur dioxide (SO2) test IEC 60068-2-42 Kc: 96 h at 25 ppm SO2, 25 °C, 75 %rH
- 3) Hydrogen sulfide (H2S) test IEC 60068-2-43 Kd: 96 h at 12 ppm H2S, 25 °C, 75 %rH

#### SOLDERLESS COMPLIANT PRESS-FIT CHARACTERISTICS:

#### PRESS-FIT CHARACTERISTICS MEASURED ACC. TO IEC 60352-5

- Press-in force: 90 N max. (at min. hole dia.) / 65 N typ.
- Push-out force: 30 N min. (at max. hole dia.) / 50 N typ.
- Push-out 3rd cycle: 20 N min. (at max. hole dia.)

#### **PCB HOLE DIMENSIONS**

- 2.54 mm grid: Finished hole Ø: 1 + 0.09/-0.06 mm | Drilled hole Ø: 1.15  $\pm$  0.02 mm

- Interstitial grid: Finished hole Ø: 0.7 + 0.09/-0.06 mm | Drilled hole Ø: 0.8  $\pm$  0.02 mm

#### **PCB HOLE PLATING**

- PCB surface finish: Hole plating
- Tin: 5-15 μm tin over min. 25 μm copper
- Copper: min. 25 μm copper
- Gold over nickel: 0.05-0.2  $\mu m$  gold over 2.5-5  $\mu m$  nickel over min. 25  $\mu m$  copper